



1765/11
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[10191/1629]

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Inventor(s) : LAERMER et al. Confirmation No.: 5642
Serial No. : 09/720,761
Filed : March 26, 2001
For : METHOD OF PLASMA ETCHING OF SILICON
Examiner : K. Chen
Art Unit : 1765
Customer No. : 26646

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450 Alexandria, VA 22313-1450, on

Date 1/11/06 Atty's Reg. # 41,172

Atty's Signature

LOZ
DERVIS MAGISTRE
KENYON & KENYON

Mail Stop Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

AMENDMENT TRANSMITTAL

SIR:

Please find an Amendment transmitted herewith for filing in the above-identified patent application. Applicants respectfully request a three-month extension of time in which to respond to the office action dated July 13, 2005, for which a response period expiring on October 13, 2005 was set. The extended period expires on January 13, 2006.

Please charge the \$1,020.00 extension fee and any additional fees required to Deposit Account No. 11-0600. A duplicate copy of this Transmittal is enclosed.

Respectfully submitted,

KENYON & KENYON LLP

R: LOZ (D.No. 41,172)

By: Gerard A. Messina

Gerard A. Messina
Reg. No. 35,952

Dated: 1/11/06



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Atty's Signature DERVIS MAGISTRE
KENYON & KENYON

AMENDMENT

SIR:

In response to the Office Action dated July 13, 2005, please amend the above-identified application as set forth below.

Amendments to the Specification do not appear in this paper.

Amendments to the Claims are reflected in the listing of the claims which begins on page 2 of this paper.

Amendments to the Drawings do not appear in this paper

Remarks begin on page 6 of this paper.